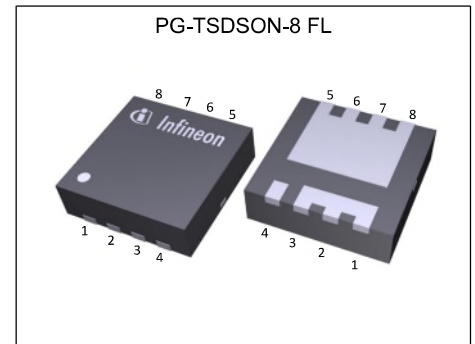


# MOSFET

## OptiMOS™5 Power-Transistor, 100 V

### Features

- Ideal for high frequency switching
- Optimized technology for DC/DC converters
- Excellent gate charge x  $R_{DS(on)}$  product (FOM)
- N-channel, normal level
- 100% avalanche tested
- Pb-free plating; RoHS compliant
- Qualified according to JEDEC<sup>1)</sup> for target applications
- Halogen-free according to IEC61249-2-21



**Table 1 Key Performance Parameters**

| Parameter        | Value | Unit       |
|------------------|-------|------------|
| $V_{DS}$         | 100   | V          |
| $R_{DS(on),max}$ | 9.7   | m $\Omega$ |
| $I_D$            | 62    | A          |



RoHS

| Type / Ordering Code | Package        | Marking | Related Links |
|----------------------|----------------|---------|---------------|
| BSZ097N10NS5         | PG-TSDSON-8 FL | 097N10N | -             |

<sup>1)</sup> J-STD20 and JESD22

## Table of Contents

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## 1 Maximum ratings

at  $T_A=25\text{ °C}$ , unless otherwise specified

**Table 2 Maximum ratings**

| Parameter                                    | Symbol            | Values |      |                | Unit | Note / Test Condition  |
|--|-------------------|--------|------|----------------|------|--|
|  |                   | Min.   | Typ. | Max.           |      |  |
| Continuous drain current <sup>1)</sup>       | $I_D$             | -      | -    | 62<br>39<br>11 | A    | $V_{GS}=10\text{ V}$ , $T_C=25\text{ °C}$<br>$V_{GS}=10\text{ V}$ , $T_C=100\text{ °C}$<br>$V_{GS}=10\text{ V}$ , $T_A=25\text{ °C}$ , $R_{thJA}=60\text{ K/W}^2)$ |
| Pulsed drain current <sup>3)</sup>           | $I_{D,pulse}$     | -      | -    | 248            | A    | $T_C=25\text{ °C}$   |
| Avalanche energy, single pulse <sup>4)</sup> | $E_{AS}$          | -      | -    | 97             | mJ   | $I_D=20\text{ A}$ , $R_{GS}=25\text{ }\Omega$  |
| Gate source voltage                          | $V_{GS}$          | -20    | -    | 20             | V    | -  |
| Power dissipation                            | $P_{tot}$         | -      | -    | 69<br>2.1      | W    | $T_C=25\text{ °C}$<br>$T_A=25\text{ °C}$ , $R_{thJA}=60\text{ K/W}^2)$   |
| Operating and storage temperature            | $T_j$ , $T_{stg}$ | -55    | -    | 150            | °C   | IEC climatic category;<br>DIN IEC 68-1: 55/150/56  |

## 2 Thermal characteristics

**Table 3 Thermal characteristics**

| Parameter  | Symbol     | Values |      |      | Unit | Note / Test Condition |
|--|------------|--------|------|------|------|-----------------------|
|  |            | Min.   | Typ. | Max. |      |                       |
| Thermal resistance, junction - case                            | $R_{thJC}$ | -      | 1.1  | 1.8  | K/W  | -                     |
| Device on PCB,<br>6 cm <sup>2</sup> cooling area <sup>2)</sup> | $R_{thJA}$ | -      | -    | 60   | K/W  | -                     |

<sup>1)</sup> Rating refers to the product only with datasheet specified absolute maximum values, maintaining case temperature at 25°C. For higher case temperature please refer to Diagram 2. De-rating will be required based on the actual environmental conditions.

<sup>2)</sup> Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm<sup>2</sup> (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air.

<sup>3)</sup> See Diagram 3 for more detailed information

<sup>4)</sup> See Diagram 13 for more detailed information

### 3 Electrical characteristics

at  $T_j=25\text{ °C}$ , unless otherwise specified

**Table 4 Static characteristics**

| Parameter                        | Symbol        | Values |             |             | Unit             | Note / Test Condition   |
|----------------------------------|---------------|--------|-------------|-------------|------------------|---|
|                                  |               | Min.   | Typ.        | Max.        |                  |   |
| Drain-source breakdown voltage   | $V_{(BR)DSS}$ | 100    | -           | -           | V                | $V_{GS}=0\text{ V}$ , $I_D=1\text{ mA}$   |
| Gate threshold voltage           | $V_{GS(th)}$  | 2.2    | 3.0         | 3.8         | V                | $V_{DS}=V_{GS}$ , $I_D=36\text{ }\mu\text{A}$   |
| Zero gate voltage drain current  | $I_{DSS}$     | -      | 0.1<br>10   | 1<br>100    | $\mu\text{A}$    | $V_{DS}=100\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=25\text{ °C}$<br>$V_{DS}=100\text{ V}$ , $V_{GS}=0\text{ V}$ , $T_j=125\text{ °C}$ |
| Gate-source leakage current      | $I_{GSS}$     | -      | 10          | 100         | nA               | $V_{GS}=20\text{ V}$ , $V_{DS}=0\text{ V}$  |
| Drain-source on-state resistance | $R_{DS(on)}$  | -      | 10.3<br>8.3 | 13.0<br>9.7 | $\text{m}\Omega$ | $V_{GS}=6\text{ V}$ , $I_D=5\text{ A}$<br>$V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$  |
| Gate resistance <sup>1)</sup>    | $R_G$         | -      | 1.2         | 1.8         | $\Omega$         | -   |
| Transconductance                 | $g_{fs}$      | 23     | 46          | -           | S                | $ V_{DS} >2 I_D /R_{DS(on)max}$ , $I_D=20\text{ A}$   |

**Table 5 Dynamic characteristics**

| Parameter                                  | Symbol       | Values |      |      | Unit | Note / Test Condition  |
|--|--------------|--------|------|------|------|--|
|  |              | Min.   | Typ. | Max. |      |  |
| Input capacitance <sup>1)</sup>            | $C_{iss}$    | -      | 1600 | 2080 | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , $f=1\text{ MHz}$                                    |
| Output capacitance <sup>1)</sup>           | $C_{oss}$    | -      | 250  | 325  | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , $f=1\text{ MHz}$                                    |
| Reverse transfer capacitance <sup>1)</sup> | $C_{riss}$   | -      | 12   | 21   | pF   | $V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , $f=1\text{ MHz}$                                    |
| Turn-on delay time                         | $t_{d(on)}$  | -      | 11   | -    | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ ,<br>$R_{G,ext}=3\text{ }\Omega$ |
| Rise time                                  | $t_r$        | -      | 5    | -    | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ ,<br>$R_{G,ext}=3\text{ }\Omega$ |
| Turn-off delay time                        | $t_{d(off)}$ | -      | 21   | -    | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ ,<br>$R_{G,ext}=3\text{ }\Omega$ |
| Fall time                                  | $t_f$        | -      | 5    | -    | ns   | $V_{DD}=50\text{ V}$ , $V_{GS}=10\text{ V}$ , $I_D=20\text{ A}$ ,<br>$R_{G,ext}=3\text{ }\Omega$ |

**Table 6 Gate charge characteristics<sup>2)</sup>**

| Parameter                          | Symbol        | Values |      |      | Unit | Note / Test Condition   |
|------------------------------------|---------------|--------|------|------|------|---|
|                                    |               | Min.   | Typ. | Max. |      |   |
| Gate to source charge              | $Q_{gs}$      | -      | 7    | -    | nC   | $V_{DD}=50\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate charge at threshold           | $Q_{g(th)}$   | -      | 4    | -    | nC   | $V_{DD}=50\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate to drain charge <sup>1)</sup> | $Q_{gd}$      | -      | 5    | 8    | nC   | $V_{DD}=50\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Switching charge                   | $Q_{sw}$      | -      | 7    | -    | nC   | $V_{DD}=50\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate charge total <sup>1)</sup>    | $Q_g$         | -      | 22   | 28   | nC   | $V_{DD}=50\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Gate plateau voltage               | $V_{plateau}$ | -      | 4.6  | -    | V    | $V_{DD}=50\text{ V}$ , $I_D=20\text{ A}$ , $V_{GS}=0\text{ to }10\text{ V}$ |
| Output charge <sup>1)</sup>        | $Q_{oss}$     | -      | 30   | 40   | nC   | $V_{DD}=50\text{ V}$ , $V_{GS}=0\text{ V}$                                  |

<sup>1)</sup> Defined by design. Not subject to production test

<sup>2)</sup> See "Gate charge waveforms" for parameter definition

**Table 7 Reverse diode**

| Parameter                             | Symbol        | Values |      |      | Unit | Note / Test Condition  |
|---------------------------------------|---------------|--------|------|------|------|--|
|                                       |               | Min.   | Typ. | Max. |      |  |
| Diode continuous forward current      | $I_S$         | -      | -    | 48   | A    | $T_C=25\text{ °C}$   |
| Diode pulse current                   | $I_{S,pulse}$ | -      | -    | 248  | A    | $T_C=25\text{ °C}$   |
| Diode forward voltage                 | $V_{SD}$      | -      | 0.9  | 1.2  | V    | $V_{GS}=0\text{ V}, I_F=20\text{ A}, T_j=25\text{ °C}$               |
| Reverse recovery time <sup>1)</sup>   | $t_{rr}$      | -      | 43   | 85   | ns   | $V_R=50\text{ V}, I_F=20\text{ A}, di_F/dt=100\text{ A}/\mu\text{s}$ |
| Reverse recovery charge <sup>1)</sup> | $Q_{rr}$      | -      | 60   | 120  | nC   | $V_R=50\text{ V}, I_F=20\text{ A}, di_F/dt=100\text{ A}/\mu\text{s}$ |

<sup>1)</sup> Defined by design. Not subject to production test

### 4 Electrical characteristics diagrams

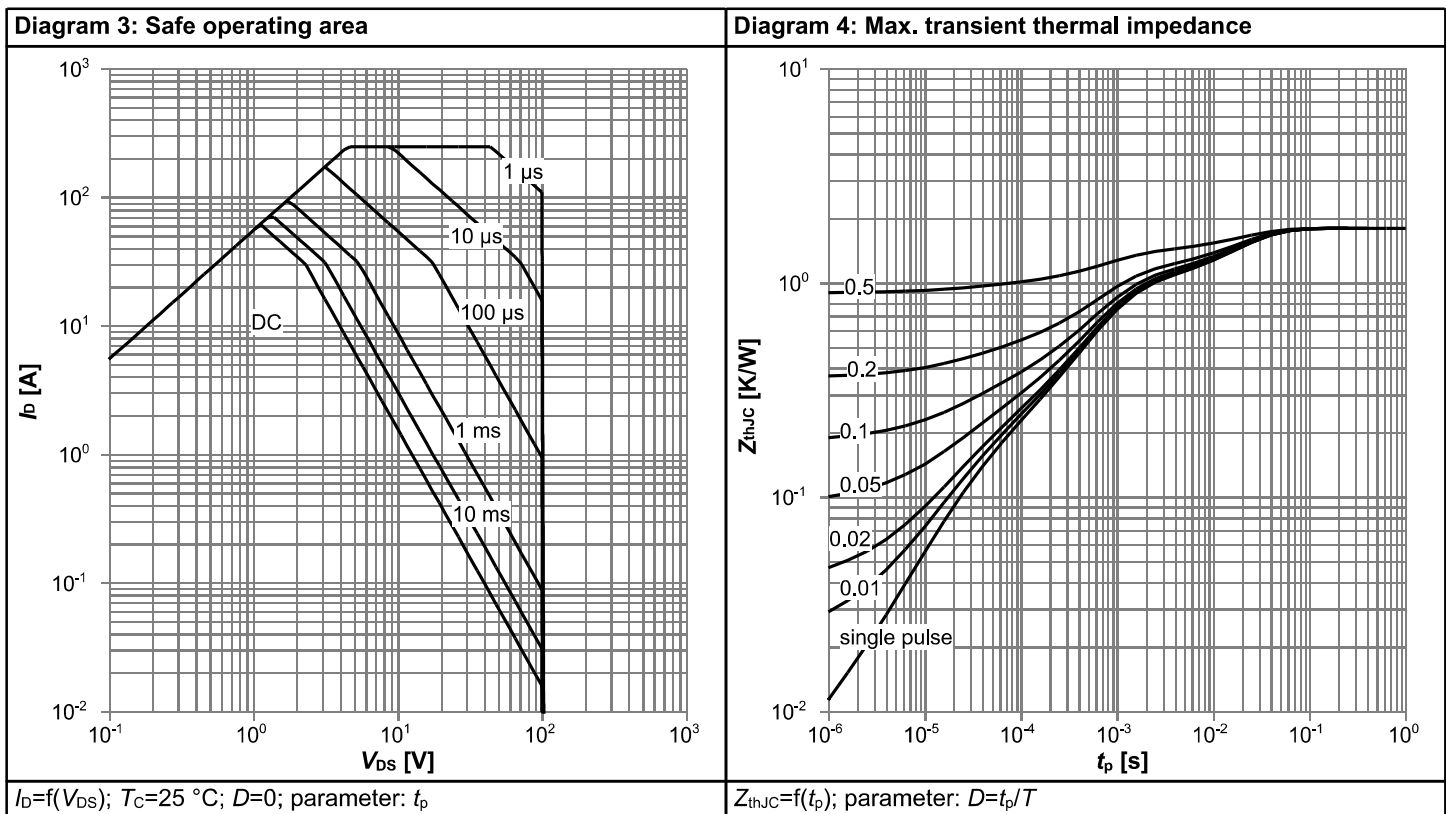
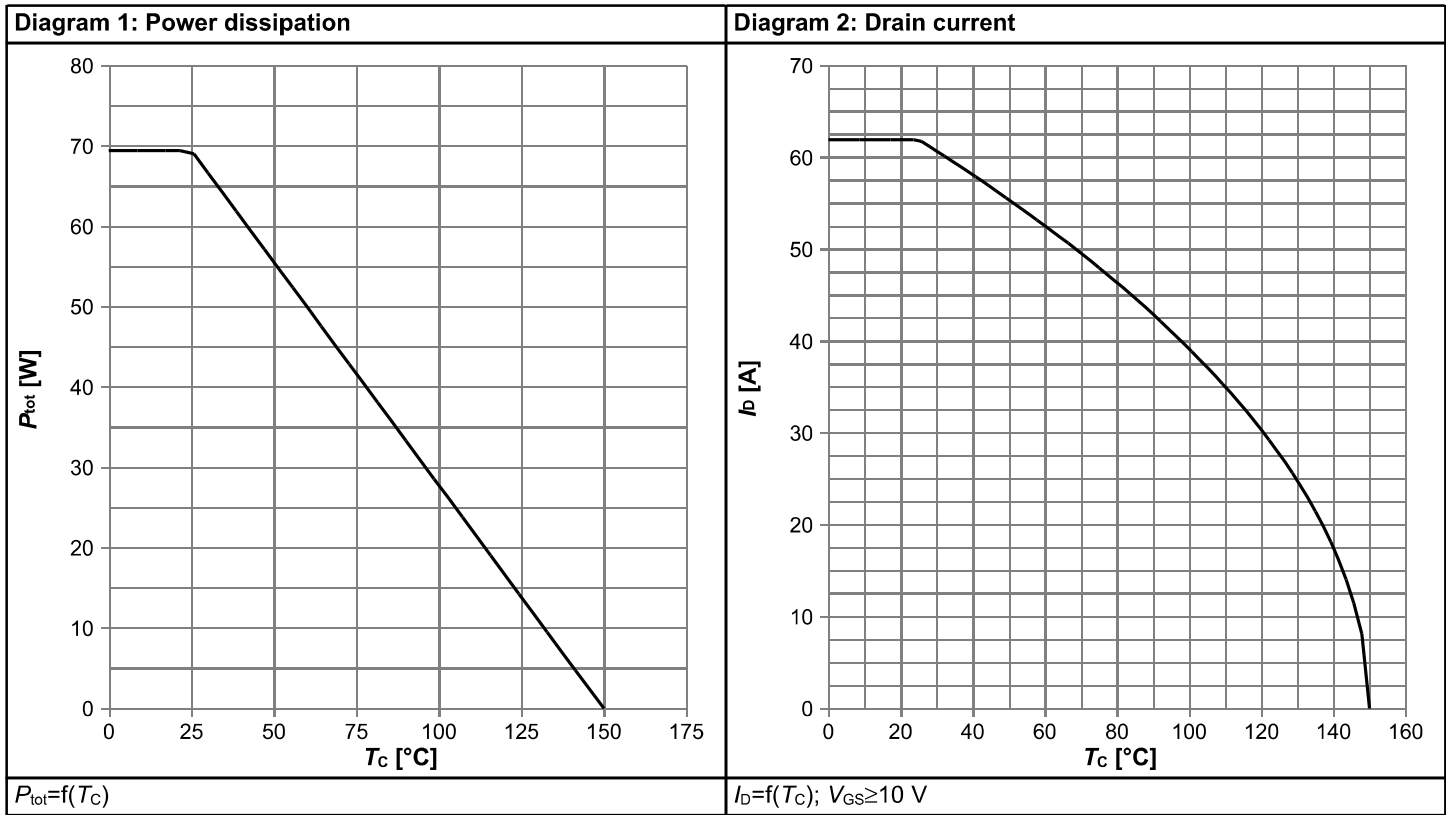
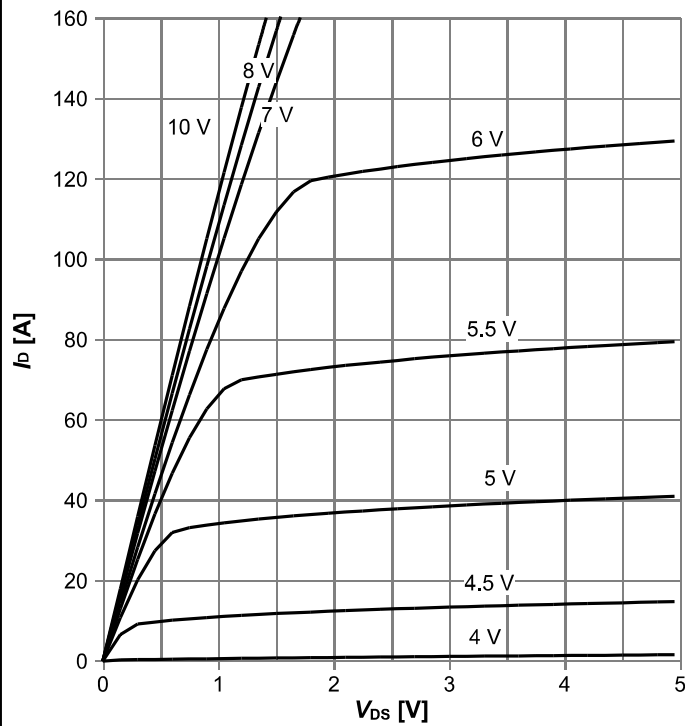
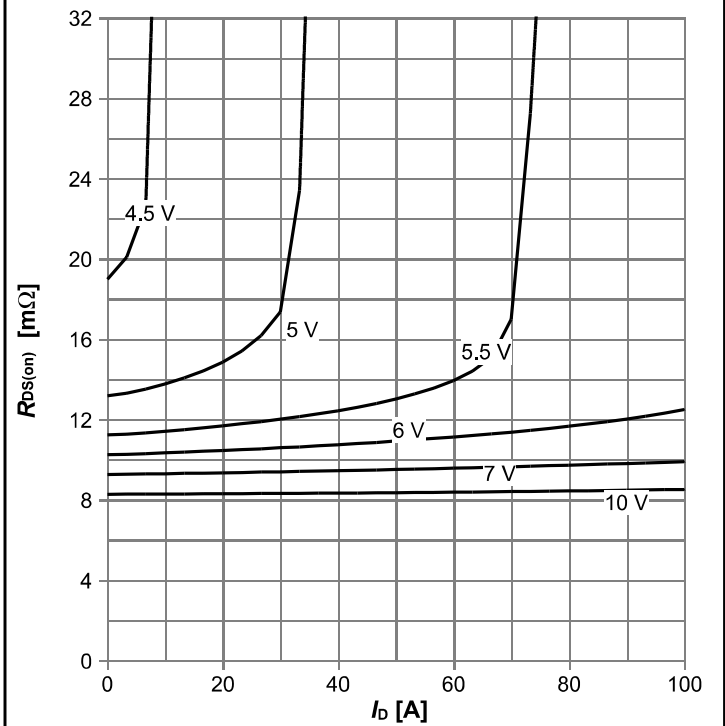


Diagram 5: Typ. output characteristics



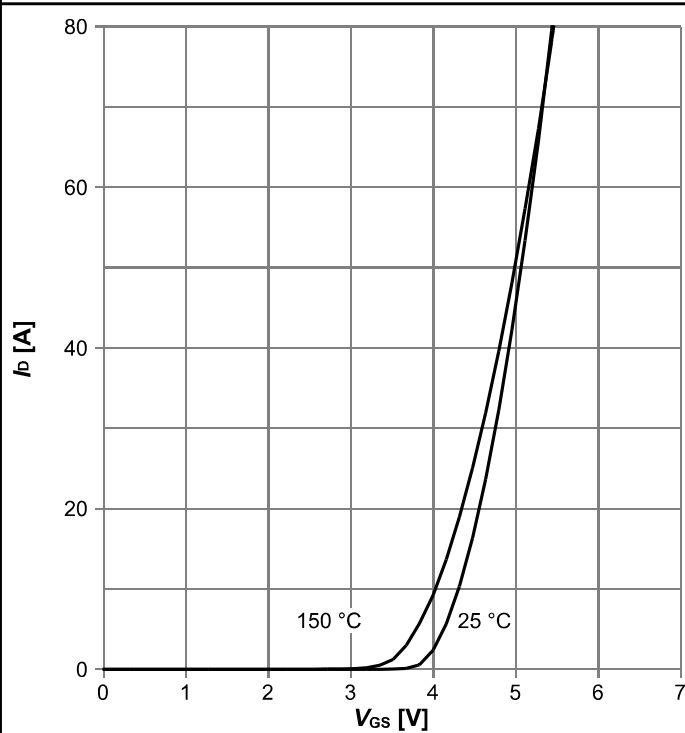
$I_D = f(V_{DS}); T_J = 25\text{ °C};$  parameter:  $V_{GS}$

Diagram 6: Typ. drain-source on resistance



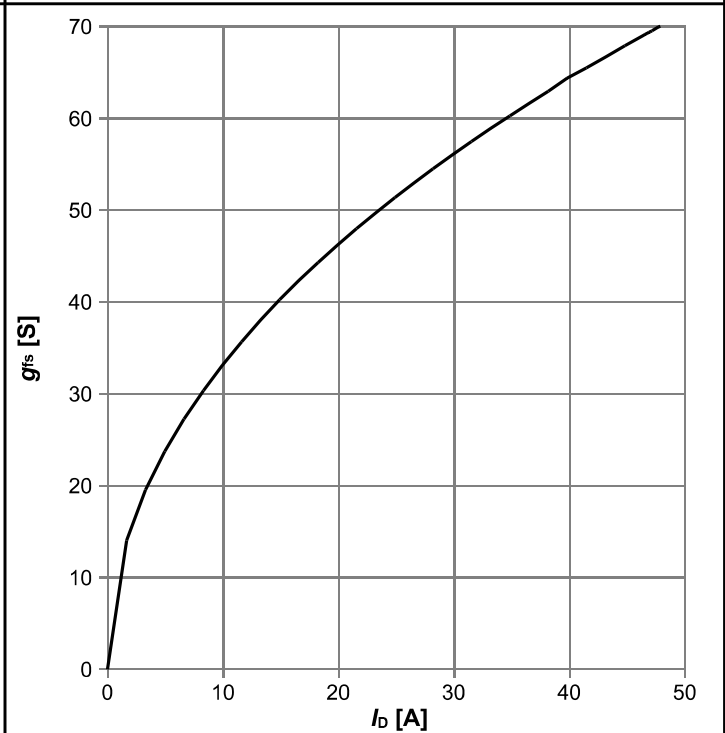
$R_{DS(on)} = f(I_D); T_J = 25\text{ °C};$  parameter:  $V_{GS}$

Diagram 7: Typ. transfer characteristics



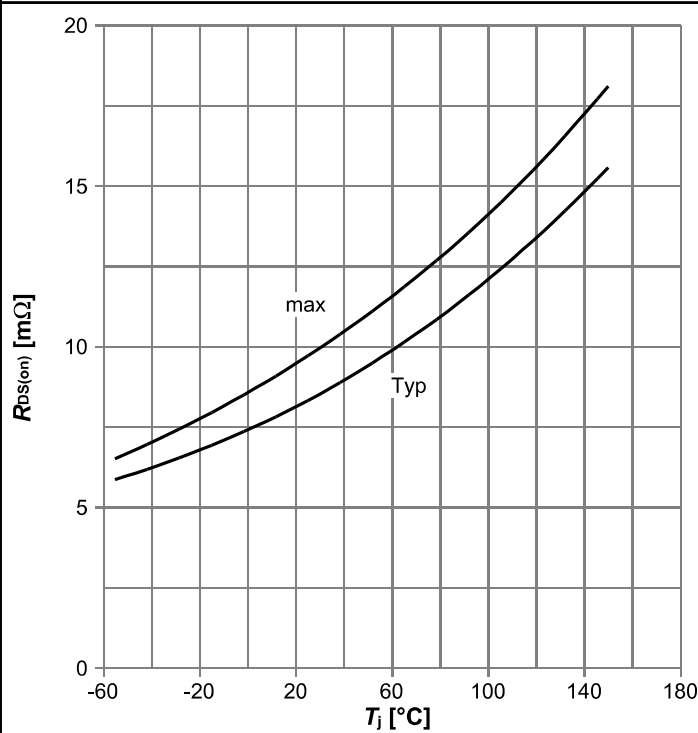
$I_D = f(V_{GS}); |V_{DS}| > 2|I_D|R_{DS(on)max};$  parameter:  $T_J$

Diagram 8: Typ. forward transconductance



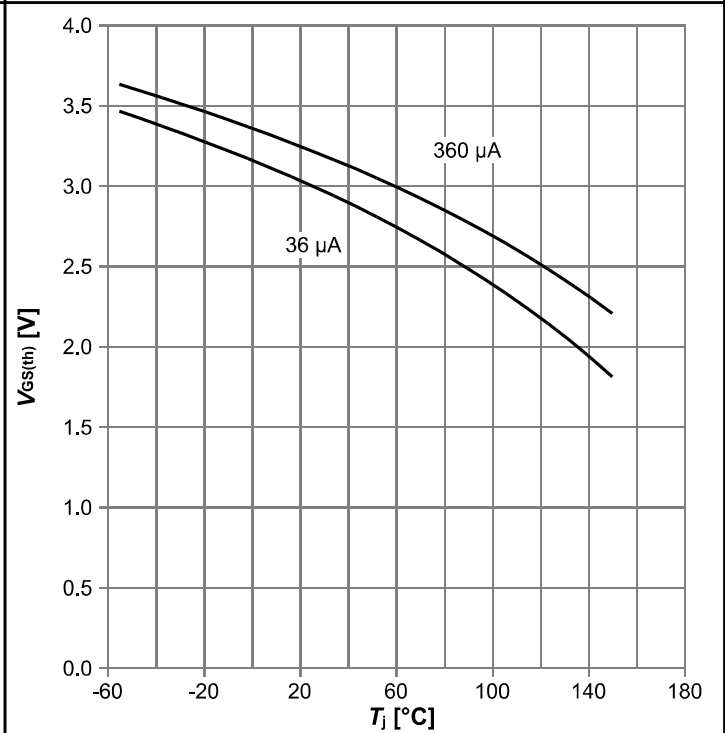
$g_{fs} = f(I_D); T_J = 25\text{ °C}$

Diagram 9: Drain-source on-state resistance



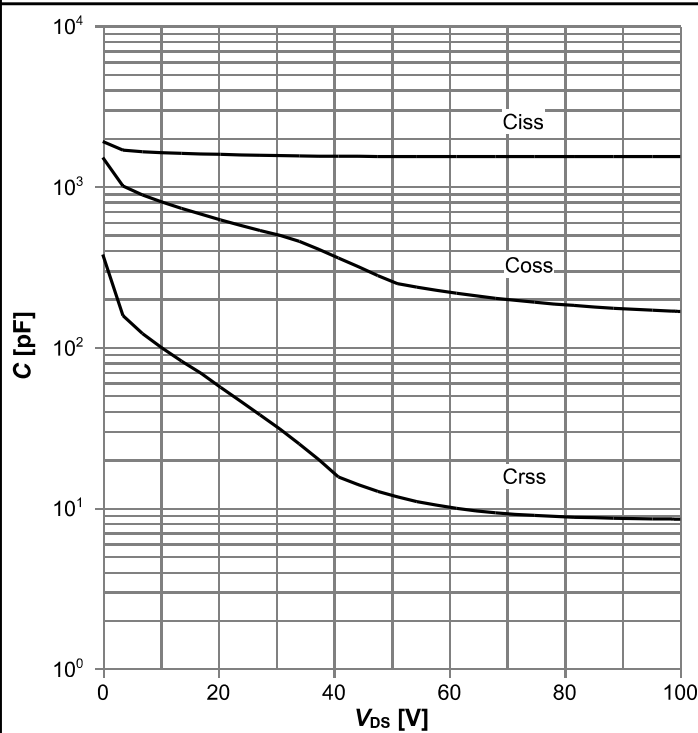
$R_{DS(on)}=f(T_j)$ ;  $I_D=20\text{ A}$ ;  $V_{GS}=10\text{ V}$

Diagram 10: Typ. gate threshold voltage



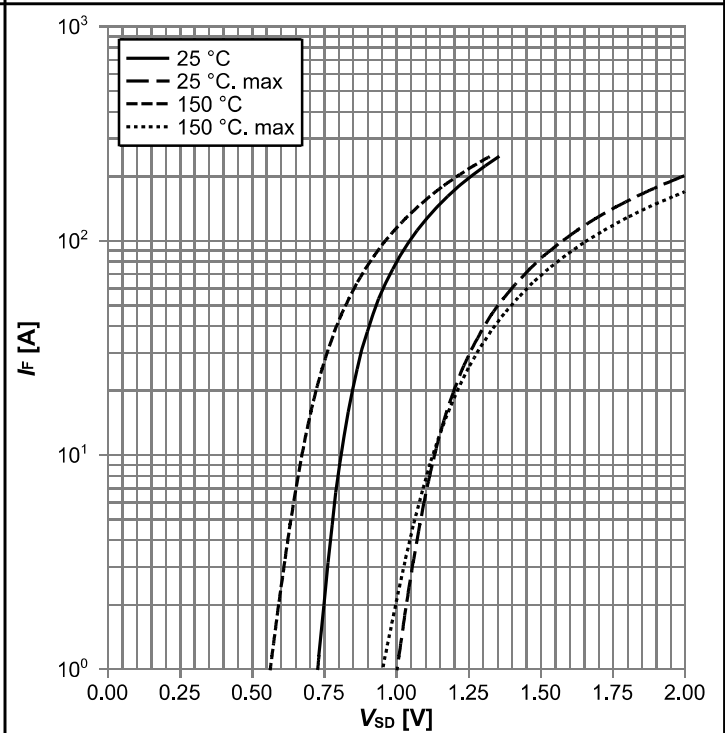
$V_{GS(th)}=f(T_j)$ ;  $V_{GS}=V_{DS}$

Diagram 11: Typ. capacitances



$C=f(V_{DS})$ ;  $V_{GS}=0\text{ V}$ ;  $f=1\text{ MHz}$

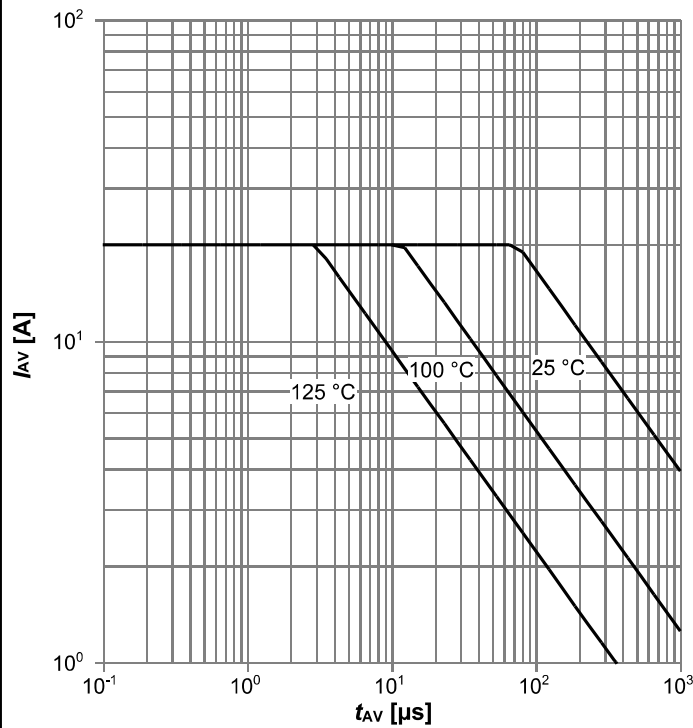
Diagram 12: Forward characteristics of reverse diode



$I_F=f(V_{SD})$ ; parameter:  $T_j$

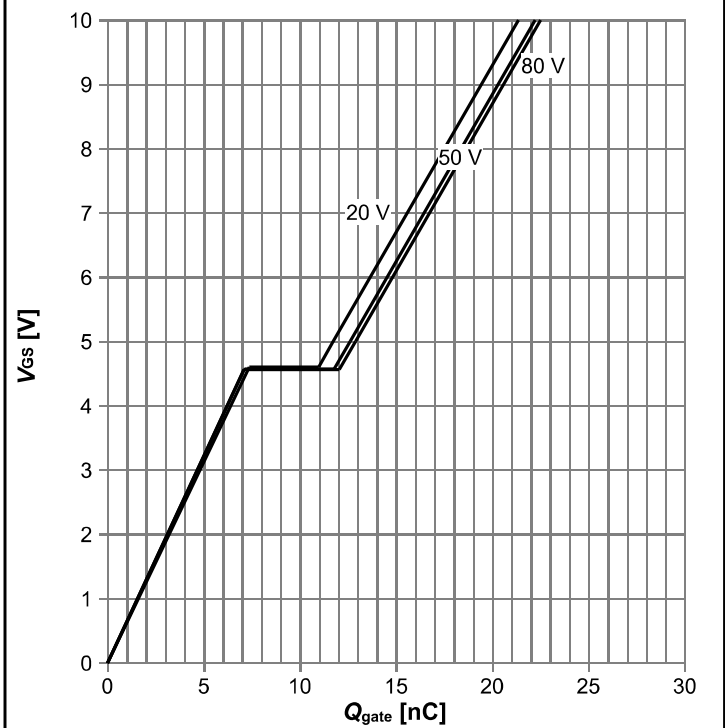


**Diagram 13: Avalanche characteristics**



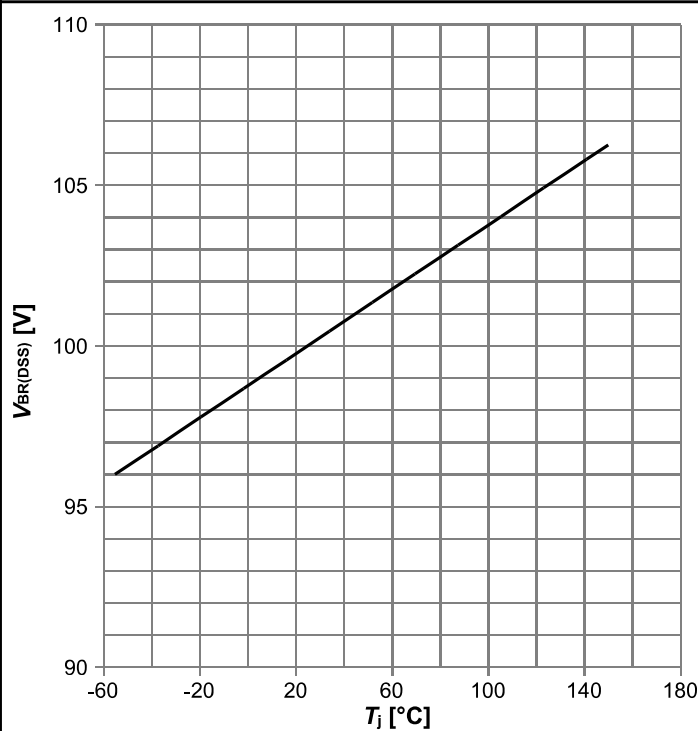
$I_{AS}=f(t_{AV}); R_{GS}=25 \Omega$ ; parameter:  $T_{j(start)}$

**Diagram 14: Typ. gate charge**



$V_{GS}=f(Q_{gate}); I_D=20 \text{ A pulsed}$ ; parameter:  $V_{DD}$

**Diagram 15: Drain-source breakdown voltage**

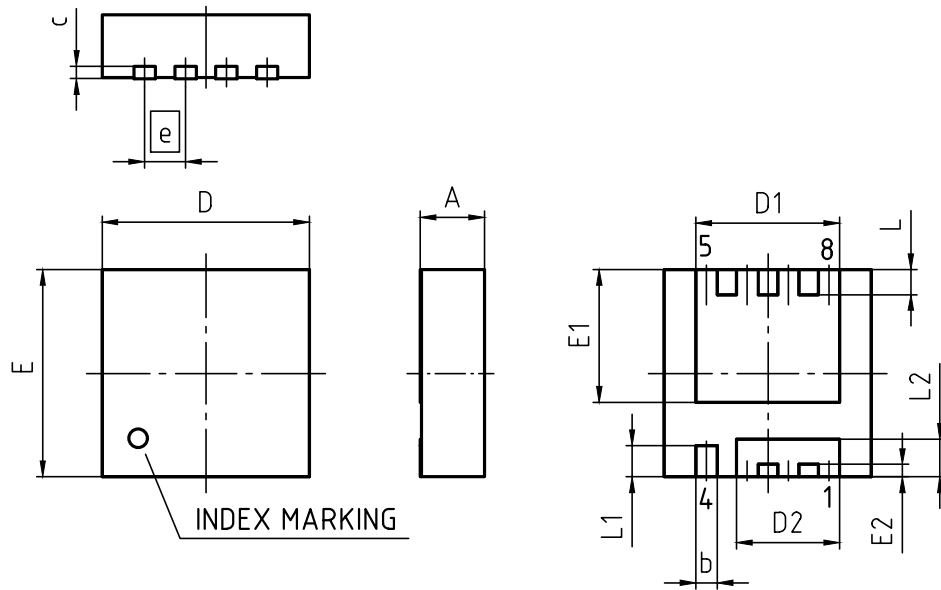


$V_{BR(DSS)}=f(T_j); I_D=1 \text{ mA}$

**Diagram Gate charge waveforms**



## 5 Package Outlines



| PACKAGE - GROUP NUMBER: PG-TSDSON-8-U03 |                  |      |
|---|------------------|------|
| REVISION: 03                            | DATE: 20.10.2020 |      |
| DIMENSIONS                              | MILLIMETERS      |      |
|   | MIN.             | MAX. |
| A                                       | 0.90             | 1.10 |
| b                                       | 0.24             | 0.44 |
| c                                       | (0.20)           |      |
| D                                       | 3.20             | 3.40 |
| D1                                      | 2.19             | 2.39 |
| D2                                      | 1.54             | 1.74 |
| E                                       | 3.20             | 3.40 |
| E1                                      | 2.01             | 2.21 |
| E2                                      | 0.10             | 0.30 |
| e                                       | 0.65             |      |
| L                                       | 0.30             | 0.50 |
| L1                                      | 0.40             | 0.60 |
| L2                                      | 0.50             | 0.70 |
| aaa                                     | 0.06             |      |

Figure 1 Outline PG-TSDSON-8 FL, dimensions in mm

## Revision History

BSZ097N10NS5

**Revision: 2021-06-18, Rev. 2.6**

Previous Revision

| Revision | Date       | Subjects (major changes since last revision) |
|----------|------------|--|
| 2.1      | 2014-05-05 | Release of Final Version                     |
| 2.2      | 2016-09-23 | Update Avalanche Energy                      |
| 2.3      | 2017-01-26 | Update Id at Tc=100°C and Ta=25°C            |
| 2.4      | 2020-11-05 | Update Max Id Current Rating                 |
| 2.5      | 2021-02-09 | Update POD                                   |
| 2.6      | 2021-06-18 | Update "Features" and IS                     |

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